File View Edit Tools Window Help

L12: (37) 4 and (substrate with contact)
L13: (6) (US-6746880-$ or US-6444027-$ or US-532441(
L14: (36) 12 not 13
L15: (426) (5 not 12) and (substrate with contact)
L16: (291) 15 and electrode
L17: (121) 16 and charge
L18: (99) 17 and current
L19: (99) 18 and surface
L20: (80) 19 and (wir$4 and (insulat$4 or dielectri(
L21: (67) 20 and etch$4
L22: (66) 21 and method
L23: (67) 21 and (process or method)
L24: (54) 17 not 23
L25: (9986) substrate and (seal$4 or (seal$4 adj (m(
L26: (103) 4 not 17
L27: (66) 26 not (12 13 14)
L28: (9910) 25 not 26
L29: (1067) 28 and (seal$4.ab. and (substrate and (I
L30: (333) 28 and (seal$4.ab. and (substrate and (b(
L31: (196) 30 and electrode

DBs: USPAT, US-PGPUB, EPO, JPO, IBM_TDB   ☑ Plurals
Default operator: OR   ☑ Highlight all hit terms initially

12 not 13

BRS term KWIC term Image Text HTML

U	1	PT	P	Document ID	Issue Dat	Pages	Title	Current OR	Current
1				US 20040171269	20040902	130	Substrate processing method	438/694	
2				US 20040094328	20040520	61	Cabled signaling system and components thereof	174/251	439/581
3				US 20040077117	20040422	26	Feedthrough design and method for a hermetically sealed microdevice	438/51	438/124; 438/126;
4				US 20030116087	20030626	16	Chamber hardware design for titanium nitride atomic layer deposition	118/715	156/345. ;
5				US 20030092261	20030515	132	Substrate processing method	438/638	257/E21. 5;
6				US 20020041443	20020411	52	Electrochromic mirrors and devices	359/603	359/265; 359/601
7				US 20020035852	20020328	21	Vacuum IG window unit with edge seal at least partially diffused at temper and completed via microwave curing, and corresponding method	65/34	65/41; 65/43;
8				US 20020020551	20020221	16	CONTROLLED-SHAPED SOLDER RESERVOIRS FOR INCREASING THE VOLUME OF SOLDER BUMPS	174/261	174/250; 174/253;
9				US 6790763 B2	20040914	128	Substrate processing method	438/622	
10				US 6701749 B2	20040309	22	Vacuum IG window unit with edge seal at least partially diffused at temper and completed via microwave curing, and corresponding method	65/41	156/104; 156/109;
11				US 6557248 B1	20030506	28	Method of fabricating an electrostatic chuck	29/825	361/234
12				US 6399169 B1	20020604	11	Vacuum IG window unit with dual peripheral seal	428/34	52/786.1 52/786.1
13				US 6392163	20020521	17	Controlled-shaped solder reservoirs for increasing the volume of	174/261	257/E21.

Hits Details HTML

Ready   NUM

L Number	Hits	Search Text	DB	Time stamp
1	1105	substrate and (seal$4 adj ring) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:26
2	1137	substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:27
3	51706	substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:02
4	103	(substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:40
5	1203	(substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:29
6	1	"6579408"	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:35
7	0	6579408.URPN.	USPAT	2004/10/20 11:35
8	0	6579408.URPN.	USPAT	2004/10/20 11:36
9	4	("5275690" | "5324410" | "5578167" | "6171437").PN.	USPAT	2004/10/20 11:36
10	4	("5275690" | "5437757" | "5542559" | "5695566").PN.	USPAT	2004/10/20 11:37
11	3	6171437.URPN.	USPAT	2004/10/20 11:37
12	37	((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:43
13	6	(US-6746880-$ or US-6444027-$ or US-5324410-$ or US-6579408-$ or US-6171437-$).did. or (US-20040104402-$).did.	USPAT; US-PGPUB	2004/10/20 11:40
14	36	(((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact)) not ((US-6746880-$ or US-6444027-$ or US-5324410-$ or US-6579408-$ or US-6171437-$).did. or (US-20040104402-$).did.)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:41
15	426	(((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:44

16	291	((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:44
17	121	(((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:45
18	99	((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge) and current	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:45
19	99	(((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge) and current) and surface	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:46
20	80	((((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge) and current) and surface) and (wir$4 and (insulat$4 or dielectric) electrolyt$3)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:01

21		67	(((((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) ·and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge) and current) and surface) and (wir$4 and (insulat$4 or dielectric) electrolyt$3)) and etch$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:48
22		66	((((((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge) and current) and surface) and (wir$4 and (insulat$4 or dielectric) electrolyt$3)) and etch$4) and method	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:48
23		67	((((((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge) and current) and surface) and (wir$4 and (insulat$4 or dielectric) electrolyt$3)) and etch$4) and (process or method)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:51

24	54	(((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge) not (((((((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge) and current) and surface) and (wir$4 and (insulat$4 or dielectric) electrolyt$3)) and etch$4) and (process or method))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:51
25	9986	substrate and (seal$4 or (seal$4 adj (mean$3 or ring))).clm. and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:02
26	103	((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:03

| 27 | 66 | (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not ((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge)) not ((((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact)) ((US-6746880-$ or US-6444027-$ or US-5324410-$ or US-6579408-$ or US-6171437-$).did. or (US-20040104402-$).did.) ((((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact)) not ((US-6746880-$ or US-6444027-$ or US-5324410-$ or US-6579408-$ or US-6171437-$).did. or (US-20040104402-$).did.))) | USPAT; US-PGPUB; EPO; JPO; IBM_TDB | 2004/10/20 12:07 |
| 28 | 9910 | (substrate and (seal$4 or (seal$4 adj (mean$3 or ring))).clm. and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not ((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge)) | USPAT; US-PGPUB; EPO; JPO; IBM_TDB | 2004/10/20 12:07 |

| 29 | 1067 | ((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))).clm. and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not ((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge))) and (seal$4.ab. and (substrate and (body or base or board or plate).ab.)) | USPAT; US-PGPUB; EPO; JPO; IBM_TDB | 2004/10/20 12:08 |
| 30 | 333 | ((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))).clm. and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not ((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge))) and (seal$4.ab. and (substrate and (body or base or board or plate)).ab.) | USPAT; US-PGPUB; EPO; JPO; IBM_TDB | 2004/10/20 12:08 |

31	196	(((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))).clm. and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not ((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge))) and (seal$4.ab. and (substrate and (body or base or board or plate)).ab.)) and electrode	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:09
32	85	(((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))).clm. and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not ((((((substrate and (seal$4 or (seal$4 adj (mean$3 or ring))) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) not (((substrate and (seal$4 adj (mean$3 or ring)) and (gas or liquid) and (open$4 or hole or trench) and (base or board or plate or body) and conduct$4) and ((outer or second or inner) adj seal$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge))) and (seal$4.ab. and (substrate and (body or base or board or plate)).ab.)) and electrode.ab.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:09
–	34	birner-albert.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:22
–	71	franosch-martin.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:07
–	57	goldbach-matthias.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:07
–	150	lehmann-volker.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:08
–	16	lutzen-jorn.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:08

-	262	birner-albert.in. franosch-martin.in. goldbach-matthias.in. lehmann-volker.in. lutzen-jorn.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:08
-	3	(birner-albert.in. franosch-martin.in. goldbach-matthias.in. lehmann-volker.in. lutzen-jorn.in.) and (seal$4 adj ring) and substrate and (board or base or plate) and (hole or open$4) and conduct$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:17
-	9	("4428815" | "4876224" | "5209833" | "5437777" | "5463526" | "5511428" | "5911461" | "6217724" | "6444027").PN.	USPAT	2004/10/19 19:11
-	15	("4322592" | "4496609" | "5192371" | "5200157" | "5242501" | "5516367" | "5679405" | "5769942" | "5856240" | "5904769" | "5960555" | "6103014" | "6127286" | "6129047" | "6184154").PN.	USPAT	2004/10/19 19:14
-	4	("5071510"|"5209833"|"5324410"|"6120657").PN	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:17
-	3	("4043894" | "4696729" | "5126031").PN.	USPAT	2004/10/19 19:18
-	12	5324410.URPN.	USPAT	2004/10/19 19:18